

Certifications

Approved by ERDF

Section

MV Semi-conductor

ApplicationField
Laboratory**PRODUCT BENEFITS**

Tool preset in factory safer than glass

TOOL CAPACITY

Diameter	15 - 240 mm 0,591 - 9,449 inch
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TOOL DIMENSIONS

Length	250 mm
Width	40 mm
Height	25 mm
Weight without box	0,19 Kg
Packaging	None

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Scraper for residues of bonded semiconductor screen.

TO DO WHAT

The tool GRI enables the user to remove bonded semiconductor screen residus.

**Options**

EGR - Pouch for GRI

Spare part

LGR - Spare balde scrape semiconductor

Associated tool

CWB/18-60-FEP - Tool to remove bonded semiconductor with chamfer on the semiconductor cutback

BRMRD1E - Tool to remove insulation

MV cables Tools

GRI



Part Number	Diameter	Tool capacity	Dimensions			Packaging
			Length	Width	Height	
GRI	15 - 240 mm 0,591 - 9,449 in		250 mm 9,843 in	40 mm 1,575 in	25 mm 0,984 in	none